

AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): Wei Pan, Yoshi Ono, David R. Evans and Sheng Teng Hsu				Docket No. SLA0515	
Serial No 09/819,296	Filing Date March 27, 2001	Examiner Hung K. Vu	Group Art Unit 2811		
Invention: Multi-Layered Barrier Metal Thin Films for Cu Interconnect By ALCVD					
<u>TO THE COMMISSIONER FOR PATENTS:</u>					
Transmitted herewith is an amendment in the above identified application.					
The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER OF EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	17 -	20 =	0	x \$18.00	\$0.00
INDEP. CLAIMS	3 -	3 =	0	x \$84.00	\$0.00
Multiple Dependent Claims (check if applicable) _____					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

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☒ No additional fee is required for amendment.

____ Please charge Deposit Account No. 19-1457 in the amount of \$0.00.

____ A duplicate copy of this sheet is enclosed.

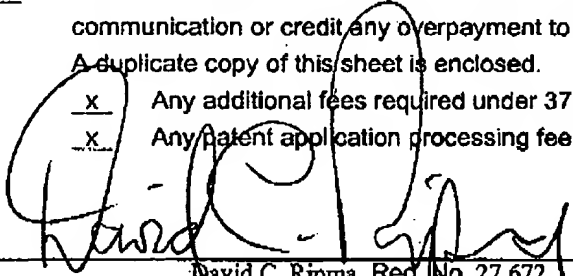
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☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-1457.

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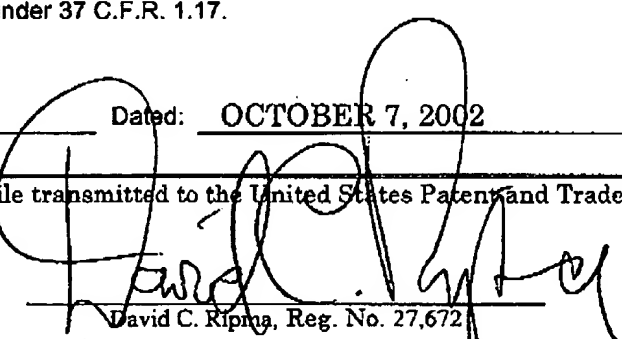
☒ Any additional fees required under 37 C.F.R. 1.16.

☒ Any patent application processing fees under 37 C.F.R. 1.17.


 David C. Ripma, Reg. No. 27,672

Dated: **OCTOBER 7, 2002**

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office under 37 C.F.R. §1.8 at Fax No. (703) 872-9318 on October 7, 2002.


 David C. Ripma, Reg. No. 27,672

Note: Each paper must have its own certificate or transmission, or this certificate must identify each submitted paper. The papers submitted include:

<input checked="" type="checkbox"/> This Amendment Transmittal Letter (Duplicate Attached)	2 page(s)
<input checked="" type="checkbox"/> Response under 37 CFR § 1.111	19 page(s)
<input checked="" type="checkbox"/> Attachments	page(s)
<input checked="" type="checkbox"/> Petition for Extension of Time under 37 C.F.R. § 1.136 (Duplicate Attached)	2 page

Total pages, including this Transmittal: 23

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	PATENT APPLICATION
)	
Inventors: Wei Pan, Yoshi Ono,)	
David R. Evans and)	Attorney Docket No.
Sheng Teng Hsu)	SLA0515
)	
Serial No.: 09/819,296)	October 7, 2002
)	
Filed: March 27, 2001)	
)	Group Art Unit 2811
Title: MULTI-LAYERED)	
BARRIER METAL)	Examiner: Vu, Hung K.
THIN FILMS FOR Cu)	
INTERCONNECT)	
BY ALCVD)	

6/a
FJONES
10-23-02

RESPONSE UNDER 37 C.F.R. § 1.111

Hon. Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to an Office Action dated June 5, 2002, please amend the above-identified application as follows.

In the Claims:

Please cancel claims 1-7 and 11.

Please amend claims 8, 10, 12 and 14.

Please add new claims 21-25 as follows.

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A clean version of the amended claims is shown on the following sheet(s), and a marked-up version, showing the changes made, is being submitted as Appendix A to this Amendment, pursuant to the amendment practice as specified in 37 C.F.R. section 1.121. Appendix B to this Amendment includes a copy of each currently pending claim in the application, including claims newly added and amended by this Response.